

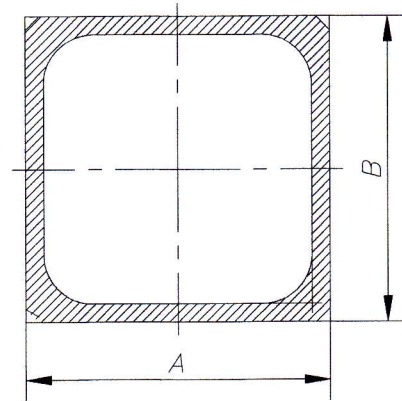


# Sierra Components, Inc.

2222 Park Place, 3-E • Minden, Nevada 89423

Phone: 775.783.4940 Fax: 775.783.4947

Type	solderable	bonderable	Chips per Wafer	Dimensions		Si-thickn. mm
				A mm	B mm	
DWN5		•	1123	4.40	2.10	0.265
DWP5		•	1123	4.40	2.10	0.265
DWN2	•	•	1204	2.95	2.95	0.265
DWN9	•	•	684	3.90	3.90	0.265
DWN17	•	•	518	4.45	4.45	0.265
DWP17	•	•	518	4.45	4.45	0.265
DWN21	•	•	346	5.40	5.40	0.265
<b>DWP21</b>	•	•	<b>346</b>	<b>5.40</b>	<b>5.40</b>	<b>0.265</b>
DWN35	•	•	259	6.20	6.20	0.265
DWP35	•	•	259	6.20	6.20	0.265
DWN50	•	•	198	7.10	7.10	0.265
DWP50	•	•	198	7.10	7.10	0.265
DWN75	•	•	125	8.70	8.70	0.265
DWP75	•	•	125	8.70	8.70	0.265
DWN110	•	•	58	12.30	12.30	0.265
DWP110	•	•	58	12.30	12.30	0.265
DWN340		•	32	16.20	16.20	0.265
DWN108	•	•	58	12.30	12.30	0.315
DWN347		•	16	25.30	18.50	0.315
Tolerance				-0.1	-0.1	±5%



APPROVED BY: MG

DIE SIZE: .212" x .212"

DATE: 12/15/15

MFG: IXYS

THICKNESS: .010"

P/N: DS145-12A/DWP21-12A